

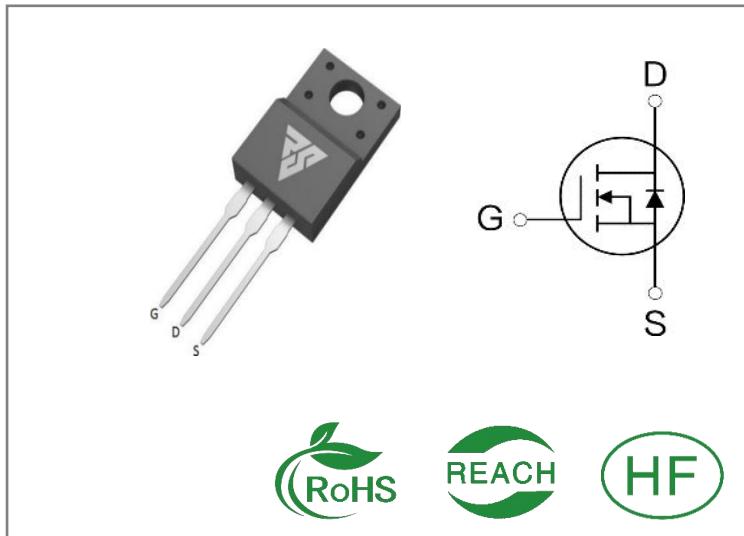
ID	R <sub>DS(ON)</sub> (Typ)	V <sub>DSS</sub>
25A	0.18Ω	500V

**Applications:**

- Switch Mode Power Supply(SMPS)
- Uninterruptible Power Supply (UPS)
- Power Factor Correction (PFC)

**Features:**

- Fast switching speed
- 100% avalanche tested
- Improved dv/dt capability


**Ordering Information**

Part Number	Package	Marking	Packing	Qty.
RS25N50F	T0-220F	RS25N50F	Tube	50 PCS

**Absolute Maximum Ratings T<sub>c</sub> = 25°C unless otherwise specified**

Symbol	Parameter	RS25N50F	Units
VDSS	Drain-to-Source Voltage	500	V
ID	Continuous Drain Current TC=25°C	25	A
IDM	Pulsed Drain Current (Note*1)	100	
PD	Power Dissipation	39	W
VGS	Gate- to- Source Voltage	±30	V
EAS	Single Pulse Avalanche Energy L = 10mH, VDD = 50V, RG = 25 Ω	871	mJ
TL TPKG	Maximum Temperature for Soldering	300 260	°C
	Leads at 0.063in(1.6mm)from Case for 10 seconds Package Body for 10 seconds		
TJ and TSTG	Operating Junction and Storage Temperature Range	-55 to 150	

\* Drain Current Limited by Maximum Junction Temperature

Caution: Stresses greater than those listed in the " Absolute Maximum Ratings" Table may cause permanent damage to the device.

**Thermal Resistance**

Symbol	Parameter	RS25N50F	Units	Test Conditions
R <sub>θJC</sub>	Junction-to-Case	3.2	°C / W	Drain lead soldered to water cooled heatsink, PD adjusted for a peak junction temperature of + 150 °C
R <sub>θJA</sub>	Junction-to-Ambient	62.5		1 cubic foot chamber, free air.

**OFF Characteristics** TJ= 25°C unless otherwise specified

Symbol	Parameter	Min.	Typ.	Max.	Units	Test Conditions
BVDSS	Drain- to- source Breakdown Voltage	500	--	--	V	V <sub>GS</sub> =0V, ID=250μA
IDSS	Drain- to- Source Leakage Current	--	--	1	μA	V <sub>DS</sub> =500V, V <sub>GS</sub> =0V
IGSS	Gate- to- Source Forward Leakage	--	--	100	nA	V <sub>GS</sub> =30V, V <sub>DS</sub> =0V
	Gate- to- Source Reverse Leakage	--	--	-100		V <sub>GS</sub> =-30V, V <sub>DS</sub> =0V

**ON Characteristics** TJ=25°C unless otherwise specified

Symbol	Parameter	Min.	Typ.	Max.	Units	Test Conditions
R <sub>D(on)</sub>	Static Drain- to- Source On-Resistance (Note*2)	--	0.18	0.24	Ω	V <sub>GS</sub> =10V, ID=12.5A
V <sub>GS(TH)</sub>	Gate Threshold Voltage	3	--	4	V	V <sub>GS</sub> =V <sub>DS</sub> , ID=250μA

**Resistive Switching Characteristics** Essentially independent of operating temperature

Symbol	Parameter	Min.	Typ.	Max.	Units	Test Conditions
t <sub>d(ON)</sub>	Turn- on Delay Time	--	53	--	nS	V <sub>DS</sub> =250V ID=25A RG=25Ω
t <sub>rise</sub>	Rise Time	--	37	--		
t <sub>d(OFF)</sub>	Turn- OFF Delay Time	--	221	--		
t <sub>fall</sub>	Fall Time	--	70	--		

**Dynamic Characteristics** Essentially independent of operating temperature

Symbol	Parameter	Min.	Typ.	Max.	Units	Test Conditions
C <sub>iss</sub>	Input Capacitance	--	3134	--	pF	V <sub>GS</sub> =0V V <sub>DS</sub> =25V f=1.0MHz
C <sub>oss</sub>	Output Capacitance	--	340	--		
C <sub>rss</sub>	Reverse Transfer Capacitance	--	13	--		
Q <sub>g</sub>	Total Gate Charge	--	60.5	--	nC	V <sub>DS</sub> =400V I <sub>D</sub> =25A V <sub>GS</sub> =10V
Q <sub>gs</sub>	Gate- to- Source Charge	--	15.5	--		
Q <sub>gd</sub>	Gate-to-Drain(" Miller") Charge	--	22	--		

**Source- Drain Diode Characteristics**

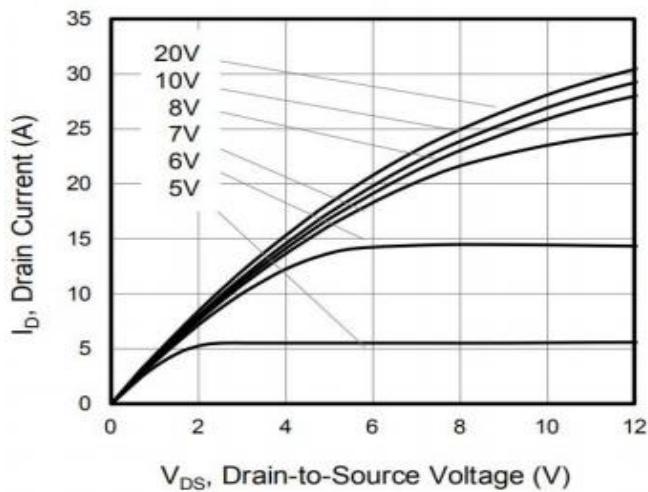
Symbol	Parameter	Min.	Typ.	Max.	Units	Test Conditions
I <sub>S</sub>	Continuous Source Current	--	--	25	A	Integral pn- diode in MOSFET
I <sub>SM</sub>	Maximum Pulsed Current	--	--	100	A	
V <sub>SD</sub>	Diode Forward Voltage	--	--	1.4	V	I <sub>S</sub> =12.5A,V <sub>GS</sub> =0V
t <sub>rr</sub>	Reverse Recovery Time	--	375	--	nS	V <sub>GS</sub> =0V I <sub>S</sub> =25A,di/dt=100 A/μs
Q <sub>rr</sub>	Reverse Recovery Charge	--	5.7	--	μC	

**Notes:**

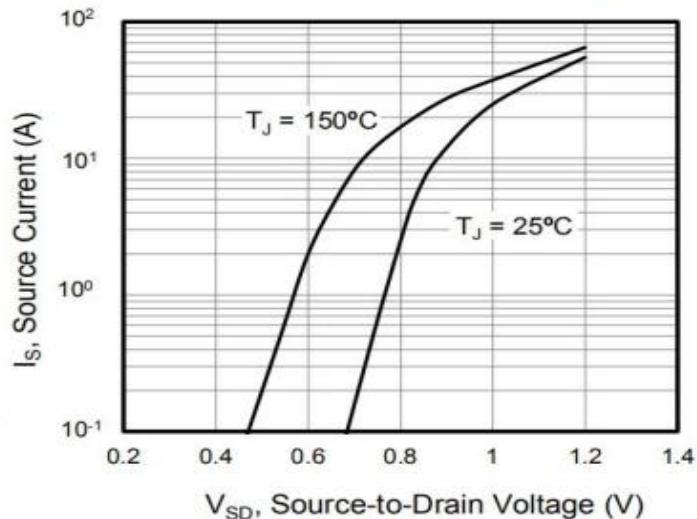
- \* 1. Repetitive rating, pulse width limited by maximum junction temperature.
- \* 2. Pulse Test: Pulse width ≤ 300μs, Duty Cycle ≤ 1%

### Typical Feature Curve

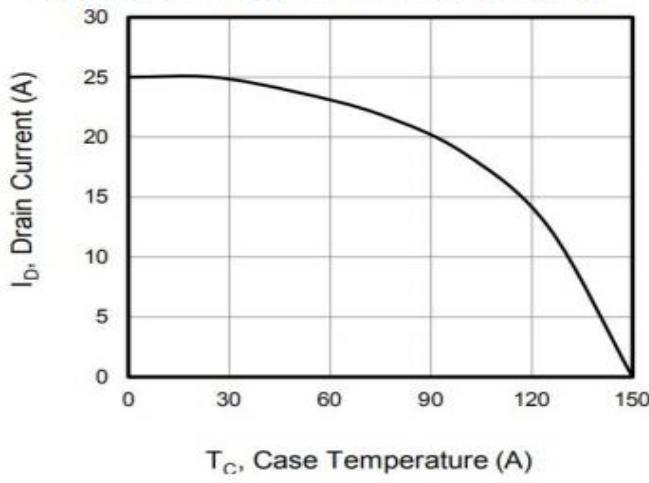
**Figure 1. Output Characteristics ( $T_J = 25^\circ\text{C}$ )**



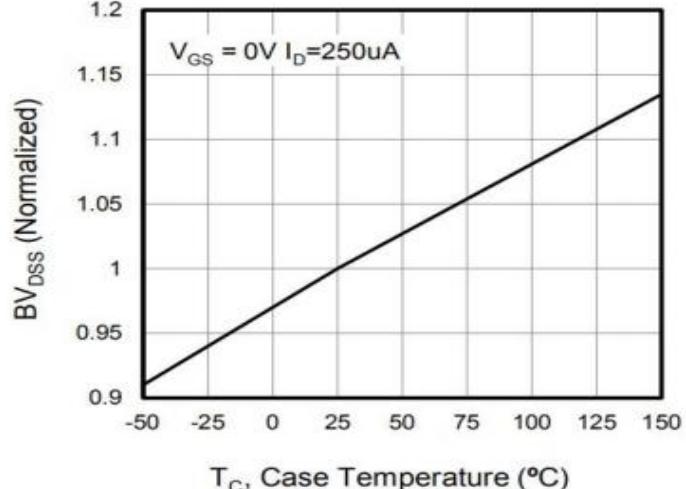
**Figure 2. Body Diode Forward Voltage**



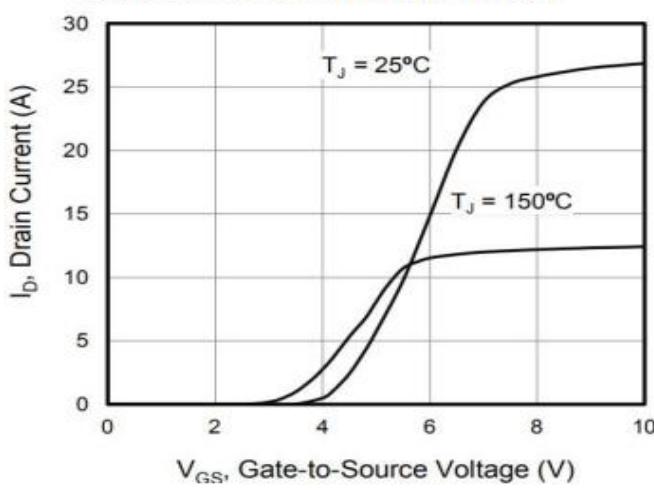
**Figure 3. Drain Current vs. Temperature**



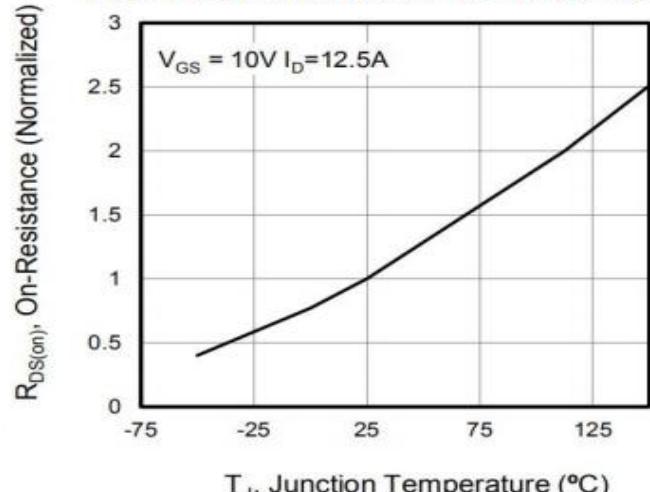
**Figure 4. BVDSS Variation vs. Temperature**

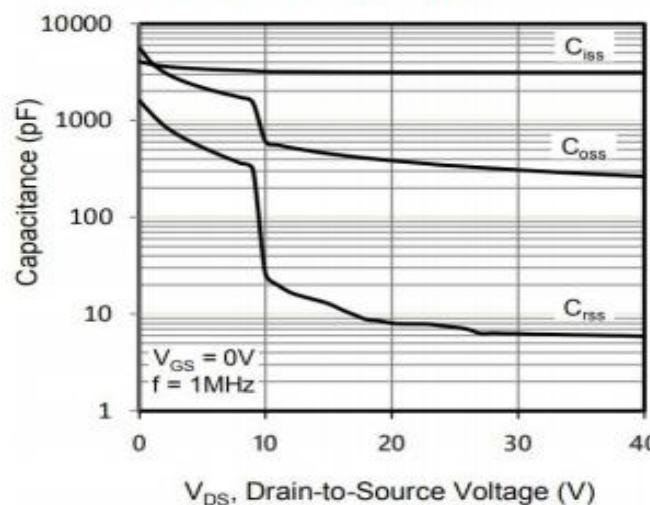
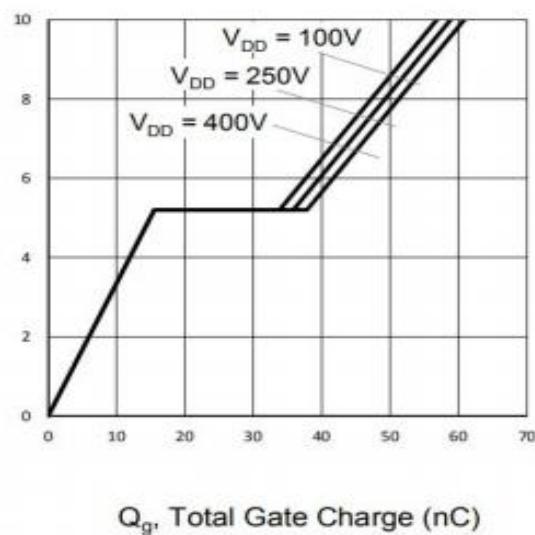
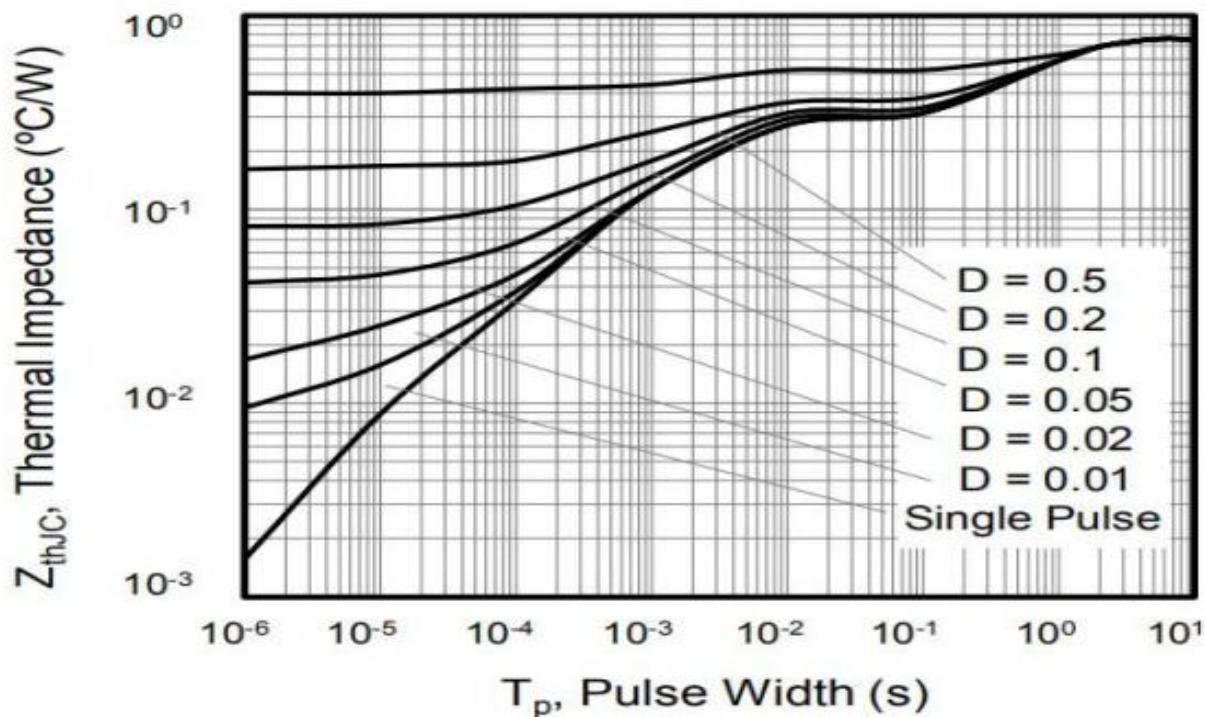


**Figure 5. Transfer Characteristics**



**Figure 6. On-Resistance vs. Temperature**



**Figure 7. Capacitance**

**Figure 8. Gate Charge**

**Figure 9. Transient Thermal Impedance  
TO-220F**


### Test Circuits and Waveforms

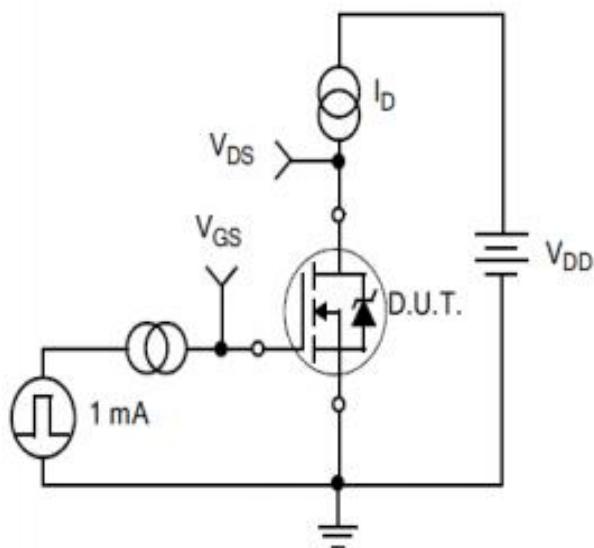


Figure10.  
Gate Charge Test Circuit

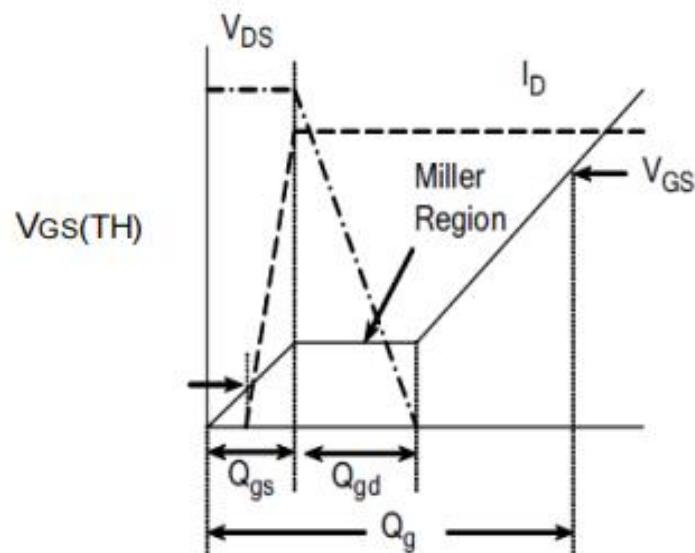


Figure11.  
Gate Charge Waveform

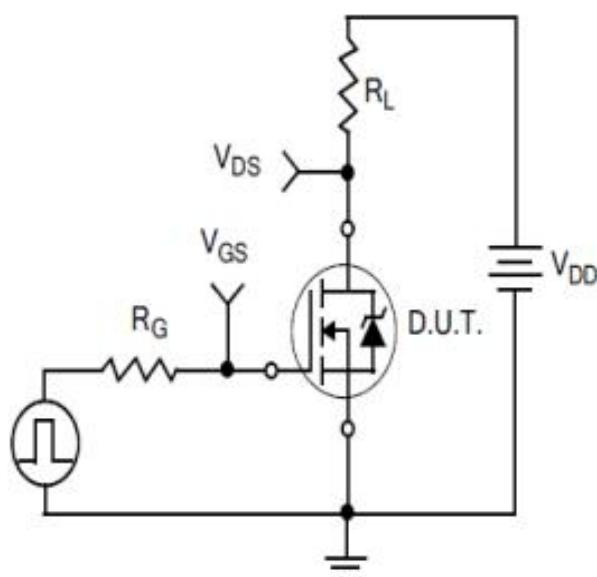


Figure12.  
Resistive Switching Test Circuit

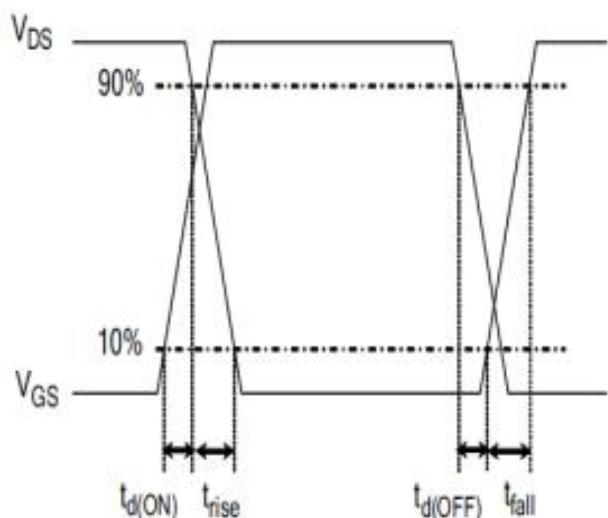


Figure13.  
Resistive Switching Waveforms

### Test Circuits and Waveforms

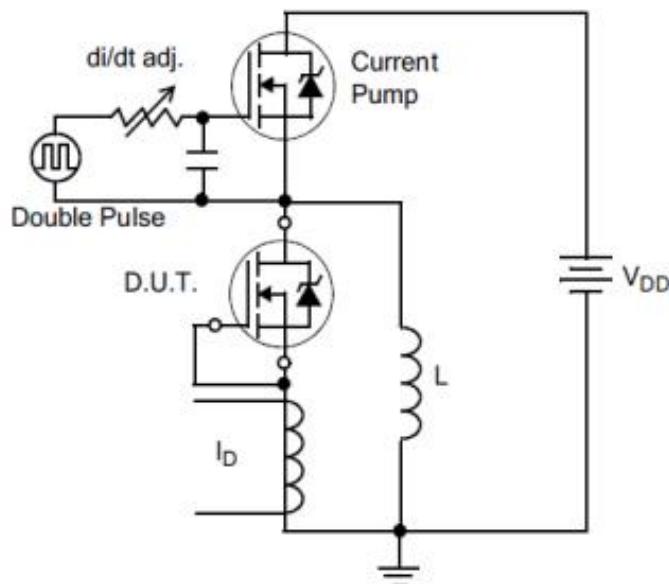


Figure 14. Diode Reverse Recovery Test Circuit

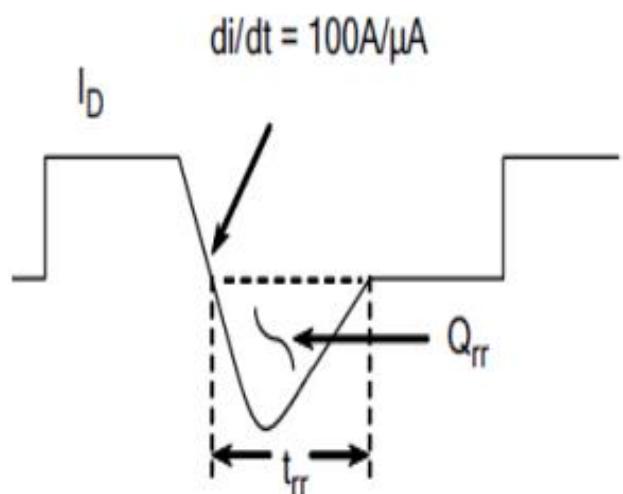


Figure 15. Diode Reverse Recovery Waveform

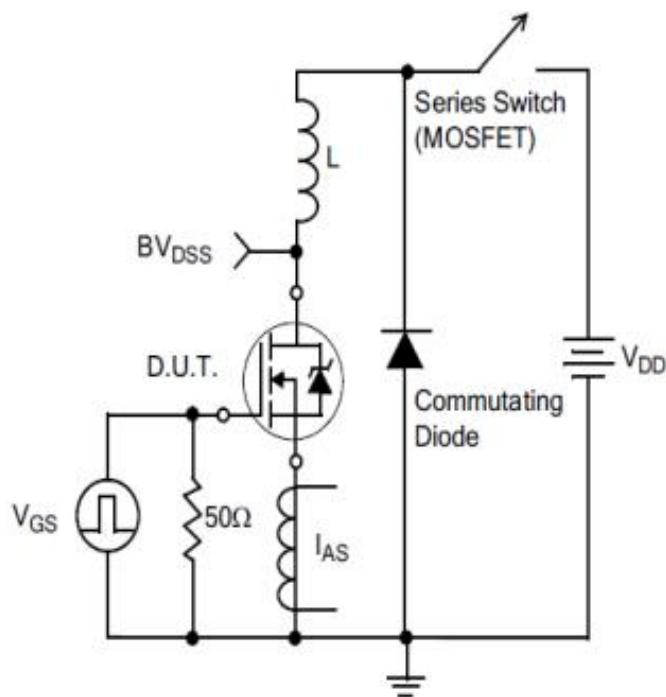
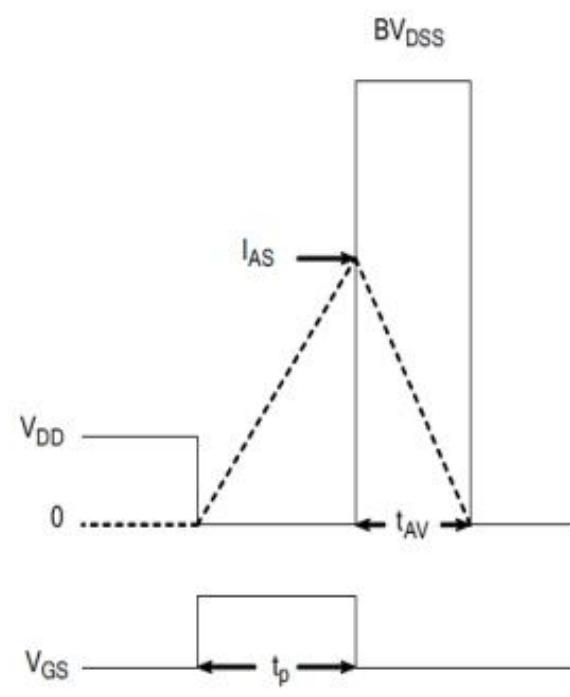
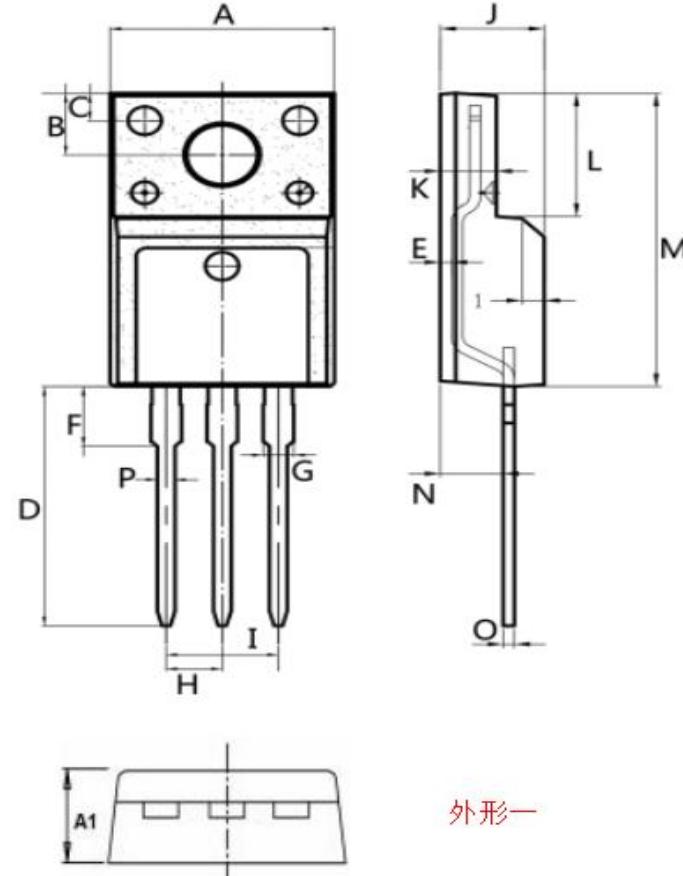


Figure 16. Unclamped Inductive Switching Test Circuit



$$E_{AS} = \frac{I_{AS}^2 L}{2}$$

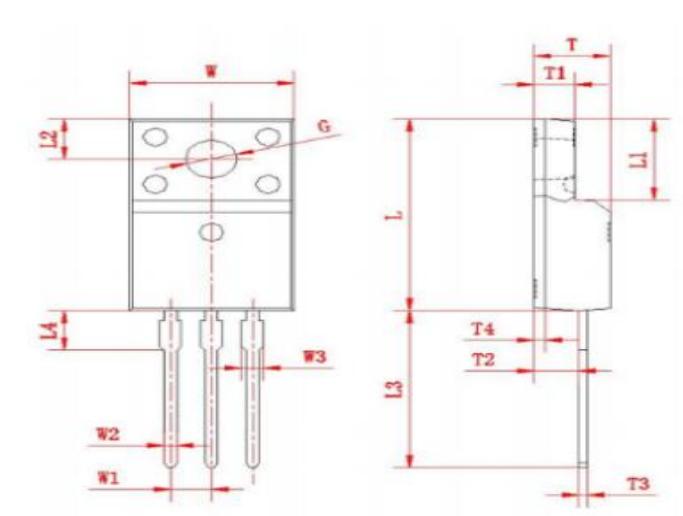
Figure 17. Unclamped Inductive Switching Waveforms

**Package outline drawing(TO-220F Unit: mm )**


外形一

Dim.	Min.	Max.
A	9.95	10.36
A1	4.5	5.0
B	2.95	3.25
C	1.25	1.45
D	12.60	13.60
E	0.40	0.60
F	2.8	3.5
G	1.30	1.45
H	(2.54)	
I	(5.08)	
J	4.60	4.75
K	2.45	2.65
L	6.5	6.8
M	15.4	16.0
N	2.25	3.05
O	0.45	0.55
P	0.70	0.90

All Dimensions in millimeter



外形二

Dim.	Min.	Max.
W	9.95	10.36
W1	(2.54)	
W2	0.70	0.90
W3	1.25	1.47
L	15.67	16.07
L1	6.48	6.88
L2	3.2	3.4
L3	12.6	13.6
L4	(3.23)	
T	4.50	4.90
T1	2.34	2.74
T2	2.25	2.95
T3	0.45	0.60
T4	(0.70)	
G	3.08	3.28

All Dimensions in millimeter

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